



MS ISSUE FEE  
PATENT  
3313-1099P

DFW

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: CHANG, Shu-Ming et al. Conf.: 2341  
Appl. No.: 10/765,961 Group: 2815  
Filed: January 29, 2004 Examiner: Sheila V. Clark  
For: WAFER LEVEL CHIP SCALE PACKAGING STRUCTURE AND METHOD  
OF FABRICATING THE SAME

LARGE ENTITY TRANSMITTAL FORM

**HANDCARRY TO:**

**U.S. Patent and Trademark Office  
220 20<sup>th</sup> Street South  
Customer Window, MS ISSUE FEE  
Crystal Plaza Two, Lobby, Room 1B03  
Arlington, VA 22202**

March 11, 2005

Sir:

Transmitted herewith please find an amendment in the above-identified application.

The enclosed document is being transmitted via the Certificate of Mailing provisions of 37 C.F.R. § 1.8.

The enclosed document is being transmitted via facsimile.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NUMBER PREVIOUSLY PAID FOR			PRESENT EXTRA	RATE	ADDITIONAL FEE
<b>TOTAL</b>	12	-	20	=	0	\$50	\$0.00
<b>INDEPENDENT</b>	2	-	3	=	0	\$200	\$0.00
<input type="checkbox"/> FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM						\$360	\$0.00
						<b>TOTAL</b>	<b>\$0.00</b>

No fee is required.

A check in the amount of \$0.00 is enclosed.

Please charge Deposit Account No. 02-2448 in the amount of \$0.00. This form is submitted in triplicate.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees.

Respectfully submitted,

BIRCH, STEWART, KOLASCH & BIRCH, LLP

By Joe McKinney Muncy \_\_\_\_\_  
Joe McKinney Muncy, #32,334

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KM/asc  
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Attachment(s)



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AND METHOD OF FABRICATING THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.312

**HANDCARRY TO:** March 11, 2005  
U.S. Patent and Trademark Office  
Customer Service Window - MS ISSUE FEE  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

Sir:

Pursuant to the provisions of 37 C.F.R. § 1.312, the following amendments and remarks are respectfully submitted in connection with the above-identified application. It is respectfully requested that the following amendments be entered without withdrawing the application from issue.

This amendment includes:

Amended Claim Set; and

Remarks.